

IEEE 802.3 - Attendance and Affiliation Sheet

Berlin, Germany - March 2015

Name	Employer	Affiliation	Mon	Tue	Wed	Thu	Credit
Abramson, David	Texas Instruments Incorporated	Texas Instruments Incorporated	1	1	1		3
Ahmad, Faisal	Akros Silicon Inc.	Akros Silicon Inc.		1	1	1	3
Andrewartha, J Michael	Microsoft Corporation	Microsoft Corporation	1	1	1	1	4
Anslow, Peter	Ciena Corporation	Ciena Corporation	1	1	1	1	4
Assouad, Simon	Broadcom Corporation	Broadcom Corporation	1	1	1	1	4
Babenko, Oleksandr	Molex Incorporated	Molex Incorporated	1	1	1	1	4
Baden, Eric	Broadcom Corporation	Broadcom Corporation	1	1	1	1	4
Baek, Kwang-Hyun	Chung-Ang University	Chung-Ang University	1	1	1	1	4
Bains, Amrik	Cisco Systems, Inc.	Cisco Systems, Inc.	1		1	1	3
Balasubramanian, Koussalya	Cisco Systems, Inc.	Cisco Systems, Inc.	1	1	1		3
Baldwin, Thananya	Ixia	Ixia		1	1	1	3
Beia, Christian	STMicroelectronics	STMicroelectronics		1	1	1	3
Belopolsky, Yakov	Self Employed	Bel Stewart Connector		1	1		2
Bergner, Bert	Tyco Electronics AMP GmbH	TE Connectivity	1	1	1	1	4
Bhatt, Vipul	Cisco Systems, Inc.	Inphi Corporation		1	1	1	3
Bietti, Ivan	Marvell Semiconductor, Inc.	Marvell Semiconductor, Inc.	1	1	1	1	4
Bliss, William	Broadcom Corporation	Broadcom Corporation	1	1	1		3
bolle, philippe	Skylane optics	skylane optics international			1	1	2
Booth, Brad	Microsoft Corporation	Microsoft Corporation		1	1	1	3
Bouda, Martin	Fujitsu Laboratories of America, Inc.	Fujitsu Laboratories of America, Inc.	1	1	1	1	4
Bourgeois, Stephane	Belden	Belden	1	1	1	1	4
Brandt, David	Rockwell Automation	Rockwell Automation	1			1	2
Braun, Ralf-Peter	Deutsche Telekom AG	Deutsche Telekom AG		1	1		2
Brillhart, Theodore	Fluke Corporation	Fluke Corporation		1	1	1	3
Brooks, Paul	JDS Uniphase Corporation	JDS Uniphase Corporation	1	1	1		3
Brown, David	Semtech Ltd	Semtech Ltd	1	1	1	1	4
Brown, Matthew	Applied Micro (AMCC)	Applied Micro (AMCC)		1	1	1	3
Brown, Thomas	Vitesse Semiconductor	Vitesse Semiconductor Corporation	1	1	1	1	4
Buntz, Stefan	Daimler AG	Daimler AG	1	1	1	1	4
Bustos Heredia, Jairo	Würth Elektronik Group	Würth Elektronik Group	1	1	1	1	4

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Name	Employer	Affiliation	Mon	Tue	Wed	Thu	Credit
Carlson, Steven	High-Speed Design Inc.	Broadcom Corporation	1	1	1	1	4
Carroll, Martin	Verizon Communications	Verizon		1	1	1	3
Carty, Clark	Cisco Systems, Inc.	Cisco Systems, Inc.	1	1	1	1	4
Cates, Ron	Marvell Semiconductor, Inc.	Marvell Semiconductor, Inc.			1	1	2
Ceekala, Vijaya	Texas Instruments Incorporated	Texas Instruments Incorporated	1	1	1		3
Chadha, Mandeep	Vitesse Semiconductor Corporation	Vitesse Semiconductor Corporation	1	1	1	1	4
Chalupsky, David	Intel Corporation	Intel Corporation	1	1	1	1	4
Chang, Jacky	Hewlett-Packard Development Company	Hewlett-Packard Development Company	1	1	1	1	4
Chang, Xin	Huawei Technologies Co. Ltd	Huawei Technologies Co. Ltd	1	1	1	1	4
Chen, David	NSN, Inc.	Nokia Siemens Networks	1	1			2
Chini, Ahmad	Broadcom	broadcom	1	1	1	1	4
Chorlton, Mike	Brand-Rex Ltd	Brand-Rex Ltd	1	1	1		3
Chuang, Keng Hua	Hewlett-Packard Development Company	Hewlett-Packard Development Company	1	1	1	1	4
Cibula, Peter	Intel Corporation	Intel Corporation	1	1	1	1	4
Cole, Christopher R	Finisar Corporation	Finisar Corporation		1	1	1	3
Collings, Brandon		JDS Uniphase Corporation			1		1
Conroy, Keith	Multiply	multiply		1	1	1	3
Corbeil, Sacha	JDS Uniphase Corporation	JDS Uniphase Corporation	1	1	1	1	4
Dai, Eugene	Cox Communications Inc.	Cox Communications Inc.			1		1
Dalmia, Kamal	Aquantia	Aquantia		1	1	1	3
D'Ambrosia, John	Dell	Dell	1	1	1	1	4
Darshan, Yair	Microsemi Corporation	Microsemi Corporation			1	1	2
Dawe, Piers J G	Mellanox Technologies	Mellanox Technologies	1	1	1	1	4
Dawson, Fred	Chemours Canada Company	Chemours Canada	1	1	1	1	4
Dedic, Ian	Fujitsu Semiconductor	Socionext Europe GmbH		1	1	1	3
De Keulenaer, Timothy	Ghent University	Ghent University		1	1		2
Diab, Wael	Huawei Technologies Co. Ltd	Huawei Technologies Co. Ltd	1	1	1	1	4
DiBiasco, Eric	TE Connectivity	TE Connectivity	1	1	1	1	4
Diminico, Christopher	M C Communications, LLC	Panduit	1	1			2
Donahue, Curtis	University of New Hampshire InterOpera	UNH-IOL	1	1			2

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Name	Employer	Affiliation	Mon	Tue	Wed	Thu	Credit
Dove, Daniel	Dove Networking Solutions	Emulex -3by / Linear Technology -3bt	1	1	1	1	4
Dudek, Michael	QLogic Corporation	QLogic Corporation	1		1	1	3
Dwellely, David	Linear Technology	Linear Technology	1	1	1	1	4
Effenberger, Frank	Huawei Technologies Co. Ltd	Huawei Technologies Co. Ltd	1	1	1	1	4
Elbakoury, Hesham	Huawei Technologies Co. Ltd	Huawei Technologies Co. Ltd	1	1	1	1	4
Engels, Yvan		employer			1		1
Estes, David	Spirent Communications	Spirent Communications	1	1	1	1	4
Ewen, John	IBM	IBM	1	1	1	1	4
Faller, Josef	homefibre digital network gmbh	homefibre digital network gmbh			1	1	2
farjad, ramin		Aquantia Corp		1	1	1	3
Feyh, German	Broadcom Corporation	Broadcom Corporation	1	1	1	1	4
Filip, Jan	Maxim Integrated Products	Maxim Integrated Products		1	1		2
Flatman, Alan	LAN Technologies Corporation, Inc.	LAN Technologies Corporation, Inc.		1	1		2
Frazier, Howard	Broadcom Corporation	Broadcom Corporation	1	1	1		3
Freeburn, Paul	Avaya Inc.	Avaya Inc.		1	1	1	3
Fritsche, Matthias	HARTING Technologie Gruppe	HARTING Electronics GmbH	1	1	1	1	4
Frosch, Richard	Phihong USA Inc,	Phihong USA Inc,		1	1	1	3
fu, shiyong	Huawei Technologies Co. Ltd	Huawei Technologies Co. Ltd	1	1	1	1	4
Gardner, Andrew	Linear Technology	Linear Technology	1	1	1	1	4
Geest, Jan	FCI USA Inc.	FCI USA Inc.		1	1	1	3
Ghiasi, Ali	Ghiasi Quantum LLC	Ghiasi Quantum LLC	1	1	1	1	4
Gong, Zhigang	O-Net Communications	O-Net Communications Ltd.	1	1	1	1	4
Goor, Dave	Philips Electronics	Philips Electronics		1	1		2
Gorshe, Steven	PMC-Sierra, Inc.	PMC-Sierra, Inc.	1	1	1	1	4
Grillaert, Joost	Nexans	Nexans		1	1	1	3
Grow, Robert	RMG Consulting	RMG Consulting; KDPOF	1	1	1	1	4
Gustlin, Mark	Xilinx	Xilinx		1	1	1	3
Hahn, Sebastian	Airbus Group Innovations	Airbus Group Innovations	1	1	1	1	4
Hajduczenia, Marek	Bright House Networks	Bright House Networks	1	1	1	1	4
Hammond, Bernard	TE Connectivity	TE Connectivity	1		1	1	3

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Hayashi, Takehiro	HAT Lab., Inc.	HAT Lab., Inc.	1	1	1	1	4
Healey, Adam	Avago Technologies	Avago Technologies	1	1	1	1	4
Heath, Jeffrey	Linear Technology	Linear Technology	1	1			2
Hess, David	CORD DATA	CORD DATA		1	1	1	3
Hidaka, Yasuo	Fujitsu Laboratories of America, Inc.	Fujitsu Laboratories of America, Inc.	1	1	1	1	4
Hilgner, Michael	TE Connectivity	TE Connectivity	1	1			2
Hirai, Riu	Hitachi, Ltd.	Hitachi, Ltd.	1	1	1	1	4
Hogenmueller, Thomas	Robert Bosch GmbH	Robert Bosch GmbH	1		1	1	3
Holden, Brian	Kandou Bus SA	Kandou Bus, S.A.	1	1	1		3
Hormmeyer, Bernd	Phoenix Contact	Phoenix Contact	1		1	1	3
Huang, Liang-wei	Realtek Semiconductor Corp.	Realtek Semiconductor Corp.		1	1	1	3
HYAKUTAKE, YASUHIRO	Adamant Co., Ltd.	Adamant Co., Ltd.	1	1	1	1	4
Ingham, Jonathan	Avago Technologies	Avago Technologies		1	1	1	3
Irwin, Scott	MoSys, Inc.	MoSys, Inc.	1	1	1	1	4
ISHIBE, KAZUHIKO	Anritsu Company	Anritsu Company	1	1	1	1	4
Isono, Hideki	FUJITSU	Fujitsu Optical Components Limited	1	1	1	1	4
Issenhuth, Tom	Microsoft Corporation	Microsoft Corporation	1	1	1		3
Jackson, Kenneth	Sumitomo Electric Device Innovations, U	Sumitomo Electric Industries, LTD	1	1	1		3
Jimenez, Andrew	Anixter Inc.	Anixter Inc.		1	1		2
Jones, Chad	Cisco Systems, Inc.	Cisco Systems, Inc.		1	1	1	3
Jones, Peter	Cisco Systems, Inc.	Cisco Systems, Inc.	1	1	1	1	4
JOSEPH, ANTONY	NXP Semiconductors	NXP Semiconductors	1	1	1	1	4
Kagami, Manabu	Toyota Central R&D Labs	Toyota CRDL	1	1	1	1	4
Kang, Vincent	GUC	GUC	1	1	1	1	4
Kareti, Upen	Cisco Systems, Inc.	Cisco Systems, Inc.	1	1	1	1	4
Karinou, Fotini	HUAWEI Technologies Duesseldorf GmbH	Huawei Technologies Duesseldorf GmbH	1	1			2
Kauschke, Michael	Socionext GmbH	socionext		1			1
KAWAHARA, KEISUKE	Furukawa Electric	Furukawa Electric	1	1	1	1	4
Kawatsu, Yasuaki	Hitachi Metals, Ltd.	Hitachi Metals, Ltd.		1	1	1	3
Kelsen, Michael	Time Warner Cable Inc.	Time Warner Cable Inc.	1	1	1	1	4

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Name	Employer	Affiliation	Mon	Tue	Wed	Thu	Credit
Kim, Yongbum	Broadcom Corporation	Broadcom Corporation	1	1	1	1	4
King, Jonathan	Finisar Corporation	Finisar Corporation	1	1	1		3
Klempa, Michael	University of New Hampshire InterOpera	University of New Hampshire InterOpera	1	1	1	1	4
Kliger, Avi	Broadcom Corporation	Broadcom Corporation (Entity Member)		1	1		2
Knittle, Curtis	Cable Television Laboratories Inc. (Cable	Cable Television Laboratories Inc. (Cable	1	1		1	3
Kobayashi, Shigeru	Tyco Electronics Japan	TE Connectivity	1	1	1	1	4
Koehler, Daniel	MorethanIP GmbH	MorethanIP	1	1	1	1	4
Kojima, Keisuke	Mitsubishi Electric Research Labs (MERL)	Mitsubishi Electric Research Labs (MERL)	1	1	1	1	4
Kolze, Tom	Broadcom Corporation	Broadcom Corporation		1	1	1	3
Kramer, Glen	Broadcom Corporation	Broadcom Corporation				1	1
Krieger, Olaf	Volkswagen AG	Volkswagen AG		1			1
Krueger, Sven	HUBER+SUHNER Cube Optics AG	HUBER+SUHNER Cube Optics AG			1	1	2
Lackner, Hans	QoSCom GmbH	QoSCom - Quality in Communications - G	1	1	1	1	4
Langhammer, Martin	Altera Corporation	Altera Corporation		1	1		2
Lapak, Jeff	University of New Hampshire InterOpera	University of New Hampshire InterOpera	1	1	1	1	4
Laubach, Mark	Broadcom Corporation	Broadcom Corporation	1	1	1	1	4
Law, David	Hewlett-Packard Ltd	Hewlett-Packard Ltd	1	1	1	1	4
Le Cheminant, Greg	Agilent Technologies, Inc.	Agilent Technologies, Inc.		1	1	1	3
Lee, Arthur	MediaTek Inc.	MediaTek Inc.	1	1	1	1	4
Lewis, David	JDS Uniphase Corporation	JDS Uniphase Corporation	1	1	1	1	4
Li, Lei	Fujitsu R&D Center	FUJITSU		1	1		2
Li, Mike-Peng	Altera Corporation	Altera Corporation	1	1	1	1	4
Lichtenegger, Thomas	Avago Technologies	Avago Technologies		1	1		2
Lillie, Andrew	Intel Corporation	Intel Corporation	1	1	1	1	4
Lin, Ru	Shanghai Luster Teraband Photonics Co.,	Shanghai Luster Teraband Photonics Co.,	1	1	1	1	4
Liu, Qian	Research Institute of Telecommunicatio	Research Institute of Telecommunicatio	1		1		2
Lo, William	Marvell Semiconductor, Inc.	Marvell Semiconductor, Inc.	1	1	1	1	4
Loughnan, Dylan		Firecomms Ltd.		1	1	1	3
Lusted, Kent	Intel Corporation	Intel Corporation	1	1	1	1	4
Maguire, Valerie	The Siemon Company	The Siemon Company	1	1	1	1	4

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Maki, Jeffery	Juniper Networks, Inc.	Juniper Networks, Inc.	1	1	1	1	4
Malkemus, James	General Cable Technologies Corporation	General Cable Technologies Corporation	1	1	1	1	4
MALKIMAN, YONATAN	Mellanox Technologies	Mellanox Technologies	1	1	1		3
Marris, Arthur	Cadence Design Systems, Inc.	Cadence Design Systems, Inc.	1	1	1	1	4
mash, chris	Marvell Semiconductor, Inc.	Marvell Semiconductor, Inc.		1	1	1	3
MASUDA, TAKEO	OITDA	PETRA (Photonics Electronics Technology	1	1	1	1	4
Matheus, Kirsten	BMW Group	BMW Group	1	1	1	1	4
Matsubara, Satoshi	FUJITSU LABORATORIES LIMITED	FUJITSU LABORATORIES LIMITED		1	1	1	3
Matsuda, Naoki		National Institute of Advanced Industrial	1	1	1		3
McClellan, Brett	Marvell Semiconductor, Inc.	Marvell Semiconductor, Inc.	1	1	1	1	4
McDonough, John	NEC Corporation	NEC America		1	1	1	3
Mei, Richard	CommScope, Inc.	CommScope, Inc.	1	1	1	1	4
Mellitz, Richard	Intel Corporation	Intel Corporation	1	1	1	1	4
Moffitt, Bryan	CommScope, Inc.	CommScope, Inc.	1	1	1	1	4
Mohammadian, Ardeshir	Brocade Communications Systems, Inc.	Brocade Communications Systems, Inc.		1	1	1	3
Mooney, Paul	Spirent Communications	Spirent Communications	1	1	1	1	4
Mori, Yojiro		Nagoya University		1	1	1	3
Moritake, Toshiyuki	Japan Aviation Electronics Ind., LTD. (JAE	Japan Aviation Electronics Ind., LTD. (JAE	1	1	1		3
Mueller, Thomas	Rosenberger Hochfrequenztechnik Gmb	Rosenberger Hochfrequenztechnik Gmb	1	1		1	3
Muir, Ron	JAE	Japan Aviation Electronics Ind., LTD. (JAE	1	1	1	1	4
Muyshondt, Henry	Microchip Technology, Inc.	Microchip Technology, Inc.	1	1	1	1	4
Nakamoto, Edward	Spirent Communications	Spirent Communications	1	1	1	1	4
Nicholl, Gary	Cisco Systems, Inc.	Cisco Systems, Inc.	1	1	1	1	4
Noll, Kevin	Time Warner Cable Inc.	Time Warner Cable Inc.	1	1		1	3
Nordin, Ronald	Panduit Corp.	Panduit Corp.	1	1	1	1	4
Nowell, Mark	Cisco Systems, Inc.	Cisco Systems, Inc.	1	1	1		3
O'Brien, Tadhg	Microsemi Corporation	Microsemi Corporation		1	1		2
Ofelt, David	Juniper Networks, Inc.	Juniper Networks, Inc.	1	1	1	1	4
Ogura, Ichiro	PETRA	PETRA	1	1	1	1	4
Palkert, Thomas	EIC	Luxtera-Molex-MoSys	1			1	2

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Panguluri, Sessa	Broadcom Corporation	Broadcom Corporation	1	1	1	1	4
Pardo, Carlos	Knowledge Development for POF SL	KDPOF		1	1	1	3
PARK, MOON	OE Solutions	oe solutions	1	1	1	1	4
Parthasarathy, Vasu	Broadcom Corporation	Broadcom Corporation		1	1	1	3
Pepper, Gerald	Ixia	Ixia		1	1	1	3
Perez De Aranda Alonso, Ruben	KDPOF	KDPOF		1	1	1	3
Pierco, Ramses	Ghent University	Ghent University		1	1		2
Pischl, Neven	Broadcom Corporation	Broadcom Corporation	1	1	1	1	4
Poehmerer, Rainer	LEONI Kabel GmbH	LEONI	1	1	1		3
Powell, William	ALCATEL-LUCENT	ALCATEL-LUCENT	1	1	1	1	4
Prodan, Richard	Broadcom Corporation	Broadcom Corporation	1	1	1	1	4
Rabinovich, Rick	ALCATEL-LUCENT	ALCATEL-LUCENT ENTERPRISE	1	1	1	1	4
RAN, ADEE	Intel Corporation	Intel Corporation	1	1	1	1	4
Regev, Alon	Ixia	Ixia	1	1	1	1	4
Remein, Duane	Futurewei Technologies	Huawei Technologies Co. Ltd	1	1	1	1	4
Renteria, Victor	Bel Fuse	Bel Fuse	1	1	1	1	4
Rosbach, Martin	Nexans Cabling Solutions	Nexans SA		1	1	1	3
Roth, Christopher	Molex Incorporated	Molex Incorporated	1	1	1	1	4
Rotolo, Salvatore	STMicroelectronics	STMicroelectronics	1	1	1	1	4
Saboori, Mohammad		Pulse Electronics				1	1
Salinger, Jorge	Comcast	Comcast	1				1
Sambasivan, Sam	AT&T	AT&T	1	1	1	1	4
Schicketanz, Dieter	Consultant	CONSULTANT; Leoni kerpen	1	1	1	1	4
Schindler, Fred	Seen Simply	Seen Simply	1	1	1	1	4
Schneelee, Stefan	Airbus Group	Airbus Group	1	1	1		3
Schraps, Mathias	Audi Electronics Venture GmbH	AUDI AG; Audi Electronics Venture GmbH		1			1
Scruton, Peter	University of New Hampshire InterOperability	University of New Hampshire InterOperability	1	1	1	1	4
Sedarat, Hossein	Aquantia	Aquantia		1	1	1	3
Seo, Inshik	Lightworks Technology. Inc	Lightworks Technology Inc.	1	1	1	1	4
SERIZAWA, NAOSHI	Yazaki Corporation	Yazaki Corporation	1	1	1	1	4

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Shariff, Masood	CommScope, Inc.	CommScope, Inc.	1	1	1	1	4
Shen, Bazhong	Broadcom Corporation	Broadcom Corporation		1		1	2
shirani, ramin	Aquantia corporation	aquantia corporation		1	1	1	3
Shirao, Mizuki	Mitsubishi Electric Corporation	Mitsubishi Electric Corporation	1	1	1	1	4
Slavick, Jeff	Avago Technologies	Avago Technologies	1	1	1	1	4
Sommers, Scott	Molex Incorporated	Molex Incorporated	1	1	1	1	4
Sone, Yoshiaki	NTT	Nippon Telegraph and Telephone Corpor		1	1	1	3
Souvignier, Tom	Broadcom Corporation	Broadcom Corporation	1	1	1	1	4
Stassar, Peter	Huawei Technologies Co. Ltd	Huawei Technologies Co. Ltd	1	1	1	1	4
Steinke, Stephan	Molex Incorporated	Molex Incorporated		1	1	1	3
Stellpflug, Gregor	Socionext Europe GmbH	Socionext Europe GmbH		1	1	1	3
Stencel, Leonard	Bourns, Inc.	Bourns, Inc	1	1	1	1	4
Stone, Robert	Broadcom Corporation	Broadcom Corporation	1	1	1		3
Swanson, Steven	Corning Incorporated	Corning Incorporated		1	1	1	3
Szczepanek, Andre	Inphi Corporation	Inphi Corporation	1	1	1	1	4
Szeto, William	Xtera Communications	xtera	1	1	1	1	4
Tailor, Bharat	Semtech Canada Corporation	Semtech Canada Corporation	1	1	1	1	4
TAJIMA, AKIO	NEC Corporation	NEC Corporation	1	1	1	1	4
Tajima, Takayuki	Yazaki corporation	YAZAKI corporation	1	1	1	1	4
TAKAHARA, TOMOO	Fujitsu Optical Components Limited	FUJITSU LABORATORIES LIMITED	1	1	1	1	4
Takahashi, Satoshi	Self Employed	Self Employed	1	1	1	1	4
Takahata, Kiyoto	Nippon Telegraph and Telephone Corpor	NTT		1	1	1	3
Takai, Atsushi	Oclaro	Oclaro, Inc		1	1	1	3
Tan, Alexander	Marvell Semiconductor, Inc.	Marvell Semiconductor, Inc.	1	1		1	3
Tanaka, Toshiaki	FUJITSU LABORATORIES LIMITED	FUJITSU LABORATORIES LIMITED	1	1	1	1	4
TAZEBAY, MEHMET	Broadcom Corporation	Broadcom Corporation	1	1	1	1	4
Ten, Sergey		Corning Incorporated			1	1	2
Thaler, Patricia	Broadcom Corporation	Broadcom Corporation	1				1
Theissen, Hubert	Nexans Deutschland GmbH	Nexans Deutschland GmbH	1	1	1		3
Thompson, Geoffrey	Linear Technology	Linear Technology	1	1	1	1	4

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Tipper, Alan	Semtech	Semtech	1	1	1	1	4
Tooyserkani, Pirooz	Cisco Systems, Inc.	Cisco Systems, Inc.	1	1	1	1	4
Tracy, Nathan	TE Connectivity	TE Connectivity	1	1	1	1	4
Tremblay, David	Hewlett-Packard Ltd	Hewlett-Packard Company		1	1	1	3
Tretter, Albert	Siemens AG	Siemens AG	1	1	1	1	4
Triess, Burkhard	ETAS GmbH	Bosch/ETAS	1				1
Trowbridge, Stephen	ALCATEL-LUCENT	ALCATEL-LUCENT	1	1	1		3
Tsukamoto, Yoshihiro	Mitsubishi Rayon Co. Ltd.	Mitsubishi Rayon Co., Ltd.	1	1	1	1	4
Tu, Mike	Broadcom Corporation	Broadcom Corporation	1	1	1	1	4
Twombly, Jeff	Credo Semiconductor, Inc.	Credo Semiconductor		1	1		2
Ulrichs, Ed	Source Photonics	Source Photonics	1	1	1	1	4
Valle, Stefano	STMicroelectronics	STMicroelectronics	1	1	1	1	4
van Bokhorst, Ruud	Philips Electronics	Philips Electronics		1			1
Vanderlaan, Paul	Nexans Canada Inc.	Berk-Tek LLC	1	1	1	1	4
Villarruel, Fernando	Cisco Systems, Inc.	Cisco Systems, Inc.	1				1
Wang, Roy	Hewlett-Packard Ltd	Hewlett-Packard Company	1	1	1	1	4
Wang, Tongtong	Huawei Technologies Co. Ltd	Huawei Technologies Co. Ltd	1	1	1	1	4
Wang, Xinyuan	Huawei Technologies Co. Ltd	Huawei Technologies Co. Ltd	1	1	1	1	4
Weber, Markus	Socionext Europe GmbH	Socionext Europe GmbH		1	1	1	3
Wen, Yang	Huawei R&D USA	Huawei R&D USA	1	1	1	1	4
Wendt, Matthias	Philips Electronics	Philips Electronics	1	1	1	1	4
Wertheim, Oded	Mellanox Technologies	Mellanox Technologies	1	1	1	1	4
white, martin	Cavium Networks	Cavium Networks	1	1	1	1	4
Wienckowski, Natalie	General Motors Company	General Motors Company	1	1	1	1	4
Wilson, John	Silicon Laboratories	Silicon Laboratories		1	1		2
Winkel, Ludwig	Siemens AG	Siemens AG	1	1	1		3
Wu, Peter	Marvell Semiconductor, Inc.	Marvell Semiconductor, Inc.	1	1	1	1	4
Xu, Yu	Huawei Technologies Co. Ltd	Huawei Technologies Co. Ltd	1	1	1	1	4
Yseboodt, Lennart	Philips Electronics	Philips Electronics	1	1	1	1	4
Yu, Ting-Fa	Realtek Semiconductor Corp.	Realtek Semiconductor Corp.		1	1	1	3

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Name	Employer	Affiliation	Mon	Tue	Wed	Thu	Credit
YUKI, HAYATO	AutoNetworks Technologies, Ltd	AutoNetworks Technologies Ltd.	1	1	1	1	4
Zhuang, Yan	Huawei Technologies Co. Ltd	Huawei Technologies Co. Ltd	1	1	1	1	4
Zimmerman, George	CME Consulting	Aquantia, CommScope, Inc. & LTC	1	1	1	1	4
Zivny, Pavel	Tektronix, Inc.	Tektronix	1	1	1	1	4
Zou, Gaoling	Maxim Integrated Products	Maxim Integrated Products	1	1	1	1	4